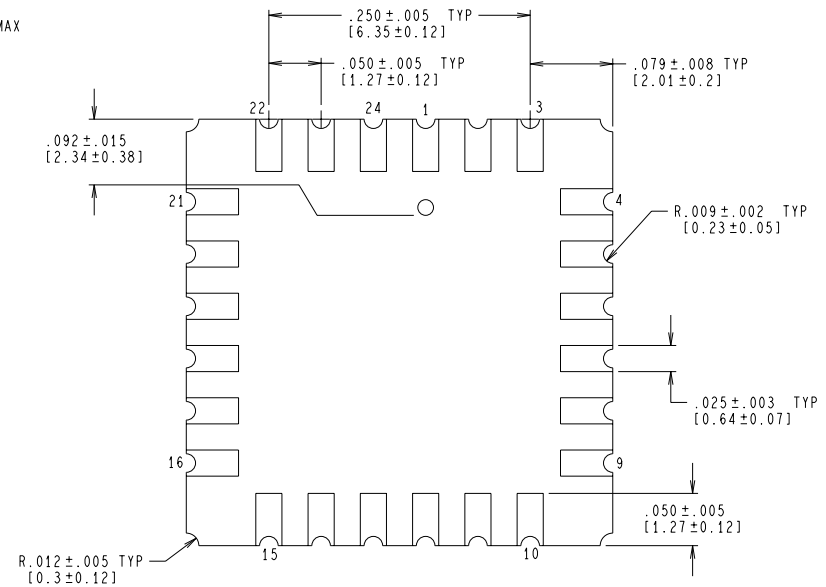
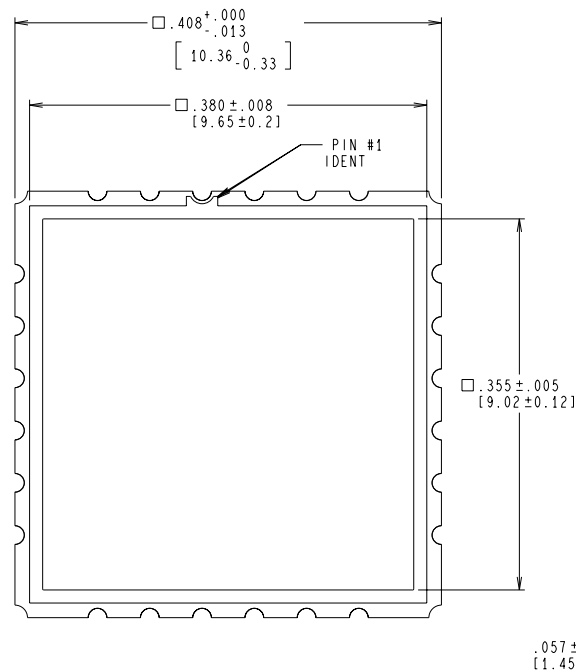


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REVISE AND REDRAW PER ECN.	10260	09/21/94	DEG/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

**MIL-M-38510
CONFIGURATION CONTROL**

**MIL/AERO
CONFIGURATION CONTROL**

NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:

- 50 MICROINCHES/12.7 MICROMETERS MINIMUM GOLD PLATING
OVER 50-350 MICROINCHES/1.27-8.89 MICROMETERS NICKEL.
- SOLDER DIP.
SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.

2. NO JEDEC REGISTRATION AS OF 9/94.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DRAWN <i>Dwayne Grady</i>		09/21/94					
DFTG. CHK.							
ENGR. CHK.							
 PROJECTION 1"=1"				SCALE	SIZE	DRAWING NUMBER	REV
				N/A	C	MKT-E24B	B
DO NOT SCALE DRAWING				SHEET 1 of 1			

**LEADLESS CHIP CARRIER,
24 TERMINAL**